REMARKS

The application contains claims 1-9. All claims are under examination. No claim is withdrawn. There is only a single ground of rejection namely alleged obviousness under 35 USC 103.

The rejection of all pending claims as obvious under 35 USC 103 over WO 99/01507 (Maeda) in view of US 5,225,484 (Shiobara) is traversed.

Maeda discloses an epoxy resin composition for encapsulating semiconductors, which are free of halogen compounds and antimony compounds and are said to be excellent in flame retardancy, as in the inventive compound.

On the other hand, Shiobara describes at column 2, lines 33 and 34 that "brominated epoxy resins are useful particularly when flame retardancy is required" and in the Examples that 10 parts of antimony trioxide (column 11, lines 5 to 6) and 7 parts of brominated epoxy resin (TABLE 2) are blended.

Accordingly, there is no motivation for combining Maeda with Shiobara, since they have adverse views on incorporating halogenated epoxy resins and antimony compounds.

Even if Maeda and Shiobara are combined, the present invention is still not expected therefrom. In Maeda, it is described that silicone oils and rubbers can be used as a stress reducing agent.

On the other hand, Shiobara describes at column 8 that:

> "It is further recommended that silicone base flexibilizers other than the above-mentioned epoxy-silicone resin copolymer be added to the epoxy resin composition of the invention, and that the inorganic fillers on the

surface are treated with two part type silicone rubber or silicone gel. The silicone base flexibilizers used herein include silicone rubber powder, silicone gel, and block polymers of phenol resin and silicone polymer. Such stress reducing agents are preferably added in amounts of about 0.5 to about 10%, more preferably about 1 to about 5% by weight based on the entire weight of the epoxy resin composition".

In the Declaration previously submitted all the following silicone fluids (i.e., silicon oil) of Polyorganosiloxane A (dimethylsilicone fluid), Polyorganosiloxane C (methylphenylsilicone fluid), Polyorganosiloxane E (alcohol-modified silicone oil), Polyorganosiloxane F (higher fatty acid-modified silicone oil) and Polyorganosiloxane G (epoxy-modified silicone oil), which are used for comparing with the inventive organopolysiloxane (D-iii) block copolymer, correspond to silicone oils described in Maeda. Moreover, silicone rubber particles (spherical silicone rubber particles) in the Declaration correspond to silicone rubber or silicon rubber powder described in Maeda and Shiobara, respectively.

According, the Examples 1 and 2 and the Comparisons 3 to 6 in the Declaration should correspond to the combinations directly led from Maeda and Shiobara. Among the combinations described in the Declaration, only the combination of component (D-iii) and zinc molybdate can impart selectively excellent flame retardance with excellent moisture resistance and solder cracking resistance.

Therefore, the results of the presently claimed invention are not expected from Maeda and Shiobara, as is evident from the Declaration in which the present invention is compared with the most closely related prior art (Maeda and Shiobara) cited by the Examiner.

In view of the above amendment, applicant believes the pending application is in condition for allowance.

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Respectfully submitted,

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